

Abstract

Method for polishing a semiconductor wafer

A method for polishing a semiconductor wafer which is polished simultaneously on both sides on the front side and on the rear side between an upper polishing plate **(11)** and a lower polishing plate **(12)**, which are respectively covered with a polishing pad **(21, 22)**, wherein a polishing gap **(x_1+x_2)** corresponding to a difference in the respective distances between those surfaces of upper polishing pad **(21)** and lower polishing pad **(22)** which come into contact with the semiconductor wafer at the inner edge **(B)** and at the outer edge **(A)** of the polishing pads **(21, 22)** is changed in its size in stages or continuously variably during the polishing method.

Figure for abstract: Fig. 1